

Honsu Group 2025Q1 Business Update

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- I 、 Company
- II 、 Performance
- III 、 R&D Investment
- IV 、 Product Strategy
- V 、 Dividend Policy



I 、 Company

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弘塑科技股份有限公司
Grand Process Technology Corporation

Y1993 Founded
Y2011 IPO (3131)
Employee : 225

□ Main Product:

**Wet Process
Equipment (Etch
/PR Strip/ Cleaner) 、
Chemical Deliver
System**



添鴻科技股份有限公司
Chemleader Corporation

Y2013 Merged
Y2002 Founded
Employee : 100

□ Main Product:

**Wet Process
Chemistry
(Etchant 、 PR
Stripper 、
Plating Additive)**



佳霖科技股份有限公司
Challentech International Corporation

Y2019 Merged
Y1987 Founded
Employee : 120

□ Main Product:

**Agent Metrology(X-
Ray 、 CSAM 、 EPD) 、
Inspection 、 Wafer
Transfer 、 Robot 、
pump Overhaul**



太引資訊系統股份有限公司
TYNE Systems Corporation

Y2018 Merged
Y2002 Founded
Employee : 30

□ Main Product:

**Software System
Design(EDA 、
SPC 、 FDC 、 Big
data) Service**

(一) Basic Information

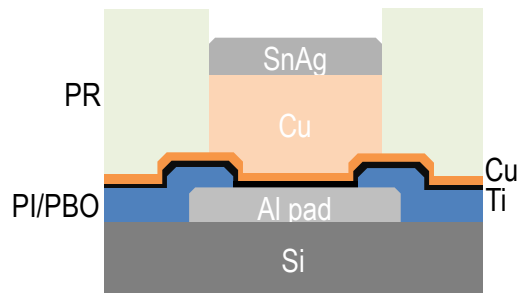
- Founded : 1993/5/7
- Capital : NTD\$ 292,216,000
- Chairman : Hoton Chang
- Service Office: HsinChu(HQ) 、 Taichung 、 Tainan 、 Kaohsiung 、 Shanghai

(二) Main Business & Customer

- Business Item :
 - a) Wet Process Equipment(Single Wafer/Wet bench/Combo System)
 - b) Wet Process Chemistry
 - c) Equipment Agent 、 Pump/Robot overhaul
 - d) Big data System Design
- Main Customer :
 - a) TW : tsmc 、 ASE 、 SPIL 、 Micron 、 PTI 、 Amkor 、 Winstek 、 WINSemi 、 EPISIL 、 Mosel 、 TSC 、 TXC 、 Innolux 、 Corning 、 GlobalWafer.....etc.
 - b) CN : TFME 、 QLE 、 Forehope 、 Corning.....etc.



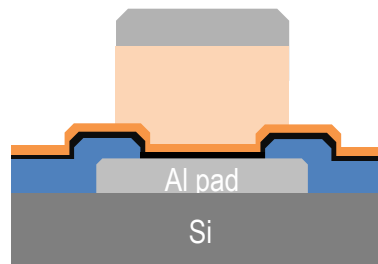
Cu Pillar Plating



- Plating performance
- Reliability

ECD Chemicals
– nt-Cu

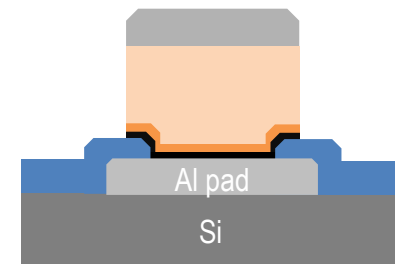
PR Stripping



- Stripper vs. PR and plating recipe
- Stripper vs. PI

Stripper

UBM Etching



- Etching selectivity
- Galvanic effect
- PR residue

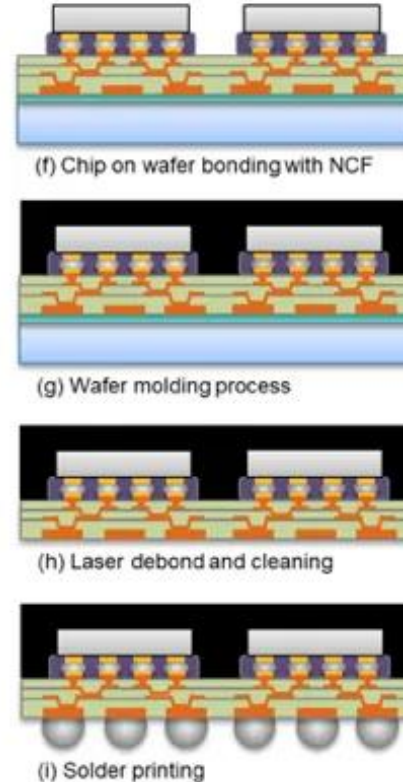
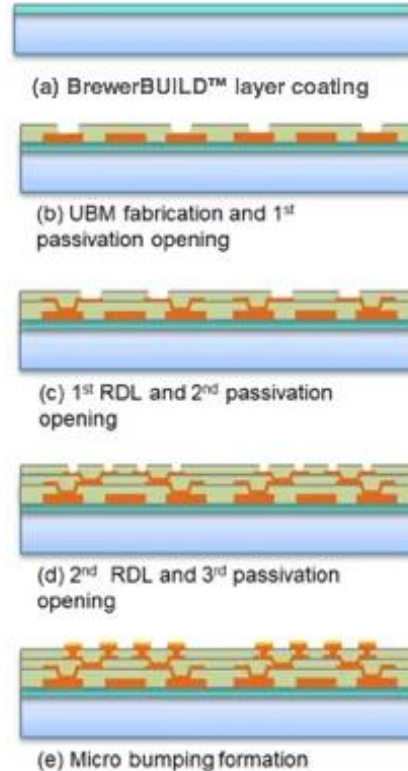
Etchant

Advanced Packaging Wet Solutions

Wafer Clean

PR Strip
UBM Etch

Surface Clean
Via Clean



Gap Clean

Debond Clean
Carrier Clean

Flux Clean
Mask Clean



Wet Bench



Single Wafer Spin



Combo System



Sales



Accumulated Installation **>1,000** sets

Patent



Accumulated IP : **149**

Avg. Annual R&D Investment : 7%~10%

Awards

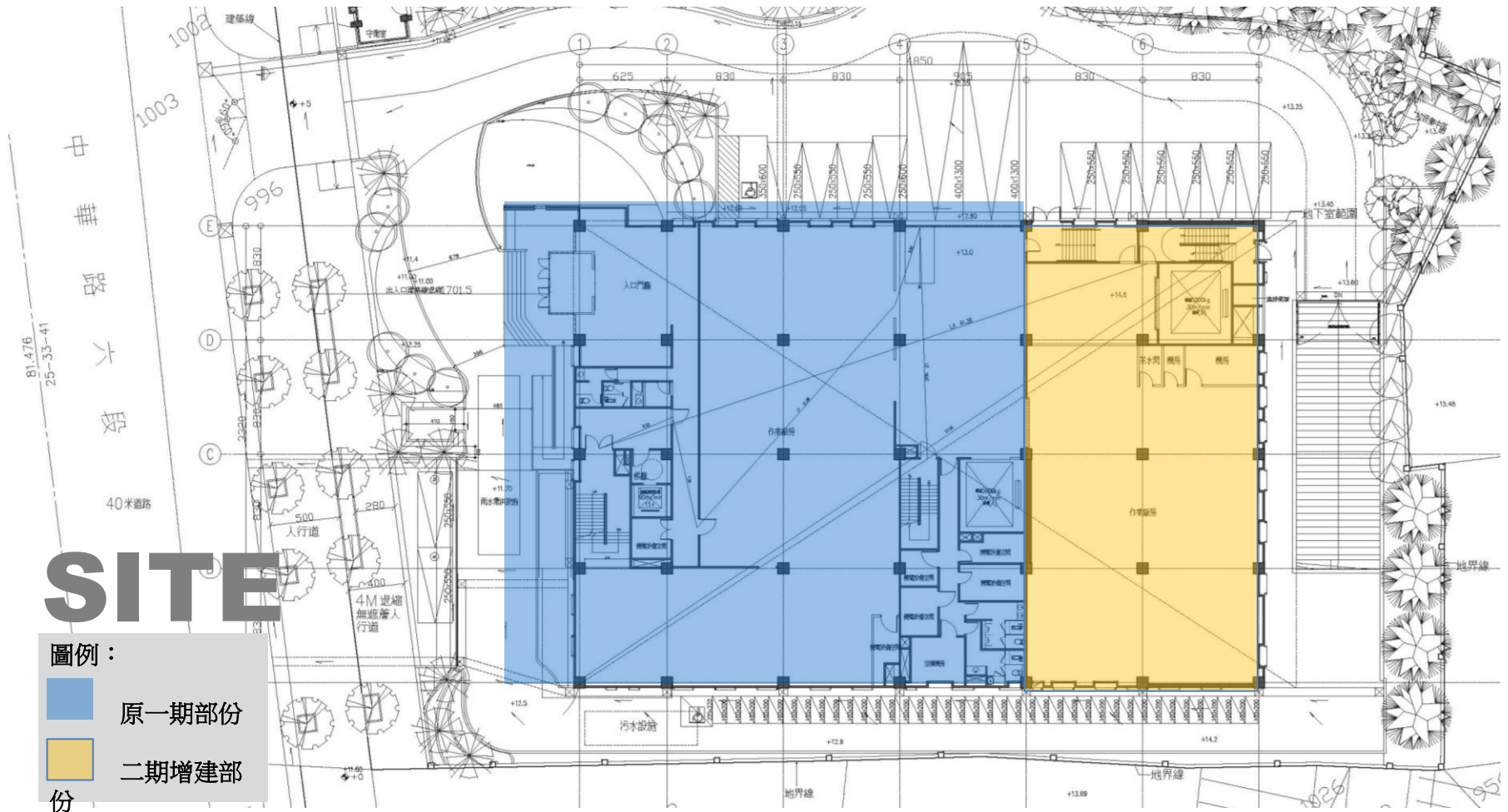


ASE Y2023 Best Supplier
tsmc Y2022 Best Supplier
tsmc Y2020 Best Supplier
SPIL Y2018 Excellent Vendor
ASE Y2018 Best Supplier
ASE Y2016 Best Supplier

Quality



-Manufacturing footprint : ~ same as Phase1



New Factory Plan - CLC

CLC T-site Factory (total 4 phase, Total Capacity : ~ 2x as H-site)
-Schedule : Phase 1 2024/Aug release production





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Income Statement

MNTD								
Year / account	2018	2019	2020	2021	2022	2023	2,024	YoY
Revenue	1,484	2,061	2,488	3,658	3,723	3,544	4,073	14.9%
Gross Profit	676	949	1,126	1,563	1,618	1,488	1,845	24.0%
OP Expense	410	534	593	739	859	793	939	18.5%
OP Net Profit	265	415	533	824	759	695	906	30.4%
Non-OP Revenue	72	(11)	(23)	10	175	54	141	161.8%
Income before Tax	338	404	510	835	934	749	1,047	39.8%
Net Profit	279	310	397	670	722	616	846	37.2%
EPS(NTD)	11.29	11.11	13.92	23.47	25.32	21.56	29.07	34.8%
Gross Margin	45.5%	46.0%	45.3%	42.7%	43.5%	42.0%	45.3%	3.3%
OP Margin	17.9%	20.1%	21.4%	22.5%	20.4%	19.6%	22.2%	2.6%
Margin before Tax	22.7%	19.6%	20.5%	22.8%	25.1%	21.1%	25.7%	4.6%

Income Statement(By Quarter)

MNTD											
Quarter / account	1Q23	2Q23	3Q23	4Q23	1Q24	2Q24	3Q24	4Q24	1Q25	QoQ	YoY
Revenue	813	862	830	1,038	898	962	992	1,222	1,241	1.5%	38.2%
Gross Profit	339	337	323	489	388	417	477	562	506	-11.1%	30.4%
OP Expense	184	172	174	263	215	216	228	280	230	-22.0%	7.0%
OP Net Profit	155	166	149	225	174	201	249	282	277	-2.0%	59.3%
Non-OP Revenue	(7)	26	46	(11)	45	45	22	45	41	-8.5%	-7.9%
Income before Tax	148	192	194	214	218	246	271	327	318	-2.8%	45.6%
Net Profit	117	153	159	188	172	205	217	251	255	1.5%	48.3%
EPS(NTD)	4.1	5.33	5.54	6.59	5.99	7.04	7.42	8.61	8.74	1.5%	45.9%
Gross Margin	41.7%	39.1%	38.8%	47.1%	43.2%	43.4%	48.1%	46.0%	40.8%	-5.2%	-2.4%
OP Margin	19.1%	19.2%	17.9%	21.7%	19.3%	20.9%	25.1%	23.1%	22.3%	-0.8%	3.0%
Margin before Tax	18.2%	22.3%	23.4%	20.6%	24.3%	25.5%	27.4%	26.8%	25.6%	-1.1%	1.3%

Year / Category		2019	2020	2021	2022	2023	2024	GM
Revenue%	Non-Consumable	62%	60%	65%	62%	63%	60%	30~50%
	Consumable	38%	40%	35%	38%	37%	40%	40~60%

Product Mix

A. Non-Consumable :

1. Equipment Manufacturing 、 Equipment Agent
2. Relocation 、 Retrofit 、 Maintenance Service
3. Software business

B. Consumable :

1. Chemistry : Solvent 、 Inorganic
2. Parts 、 Component
3. Cryo Pump 、 Robot Overhaul

Business Summary : by Area

Area	2019	2020	2021	2022	2023	2024
Taiwan	74%	80%	72%	69%	59%	70%
China	20%	13%	21%	26%	37%	25%
Others	6%	6%	6%	5%	4%	5%

2024 Oversea Market Achievement :

- A. USA : HBM
- B. Japan : PMIC
- C. Malaysia : WLPFO
- D. Singapore : WLP
- E. Italy : Silicon Wafer
- F. China : PLPFO 、 WLPFO 、 CoW 、 Hybrid Bonding 、 HBM



I 、 Company

II 、 Performance

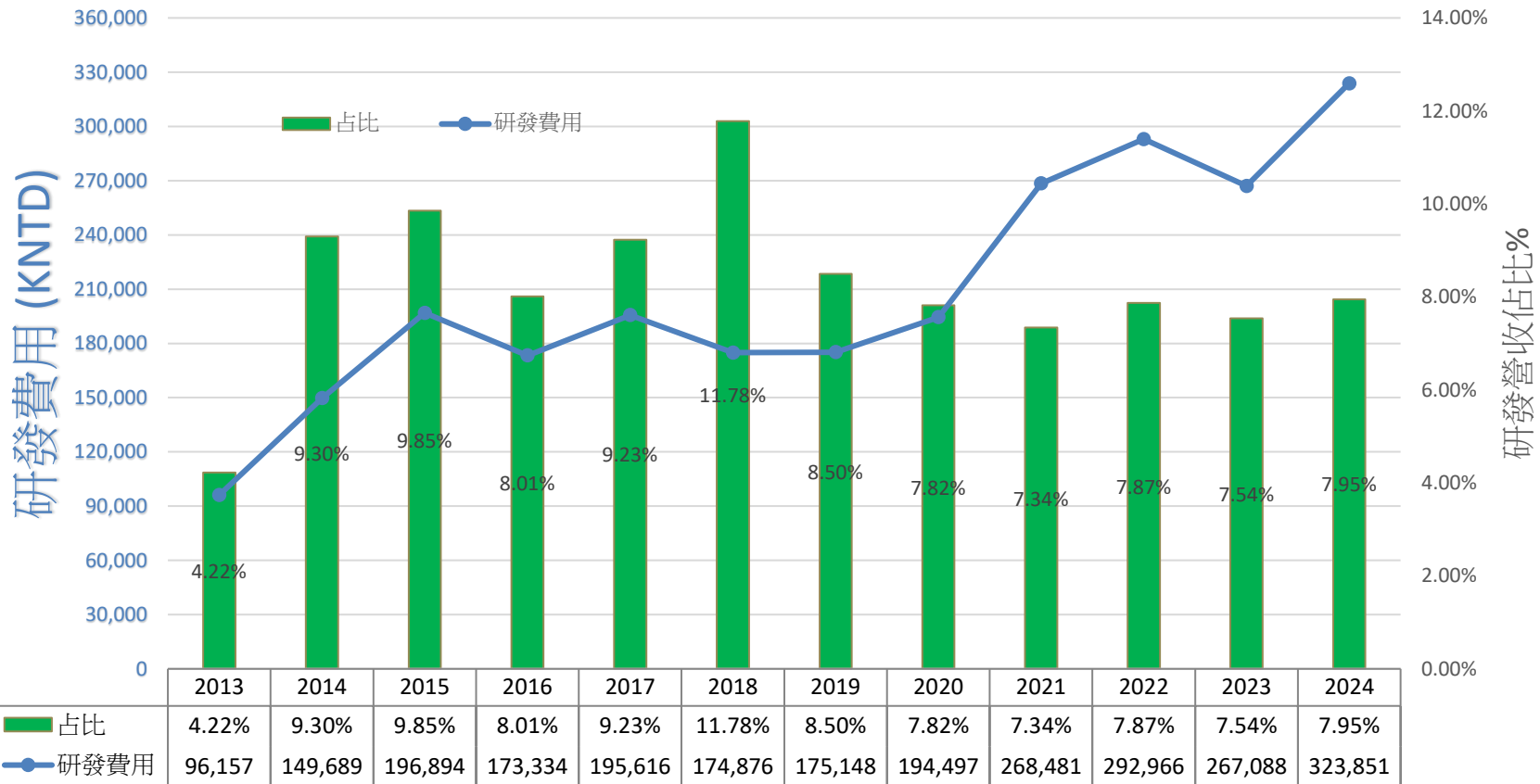
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R&D Expense Investment

弘塑科技研發費用及營收佔比(Group)





I 、 Company

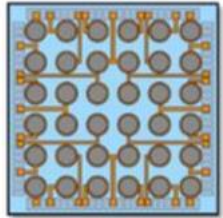
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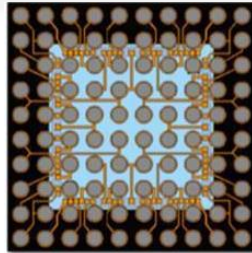
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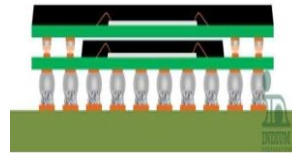
Process Application Opp.



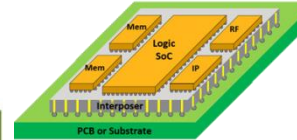
Fan-In /
WL-CSP



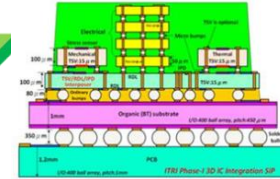
Fan-Out /
WLP/PLP



Package on
package



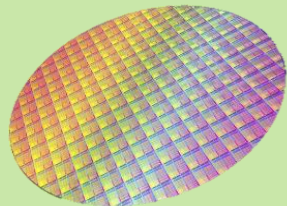
2.5D
- Fan-In/Out
- CoWoS



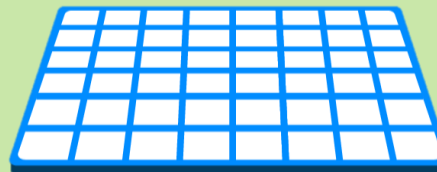
SoIC/
Hybrid Bond

*2D to 3D
Structure*

*Wide Range
Wafer Size*



75mm
100mm
125mm
150mm
200mm
300mm



300*300 mm
510*515 mm
600*600 mm

*Multi-
Application*

Advanced Package

- Flip Chip Bumping
- Fan Out Packaging
- 2.5D CoWoS
- 3D SoIC 、CPO

Compounded

- SiC
- GaAs/GaN
- InP

Automotive

- Diode
- CIS
- Micro LED

Others

- Bio Chip
- Crystal element
- IC Substrate

Product Development Focus on AI/HPC Advanced Package

■ GPTC

- Metal Etch
- PR Strip
- Cleaner

■ CLC

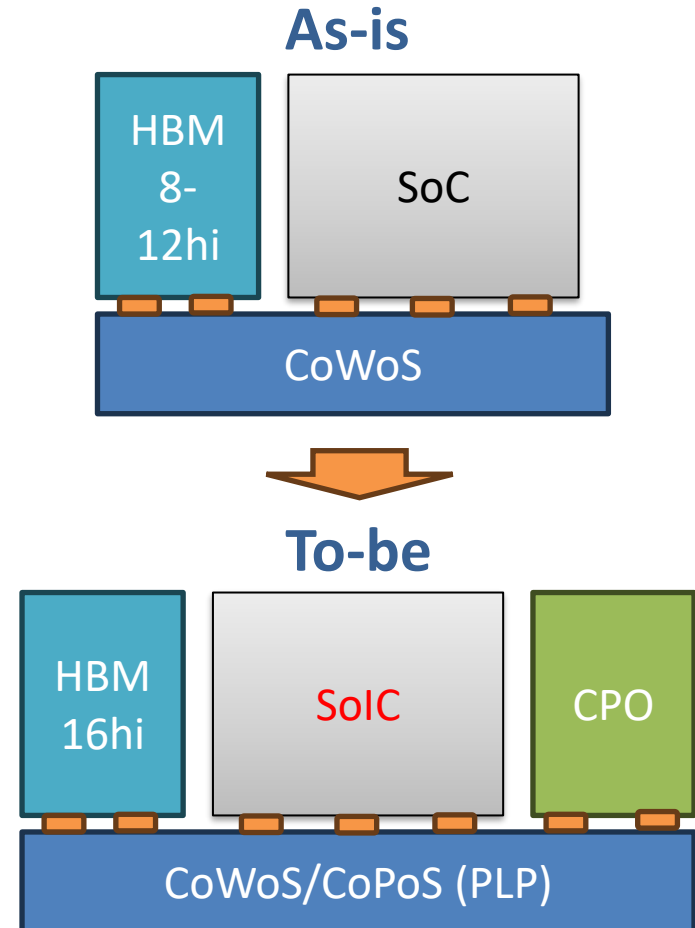
- Cu/Ti Etchant
- Environmentally PR Strip

■ CIC

- X-Ray Inspection
- CSAM Inspection
- End Point Detector for Wet Etch
- Concentration Monitor

■ TYNE

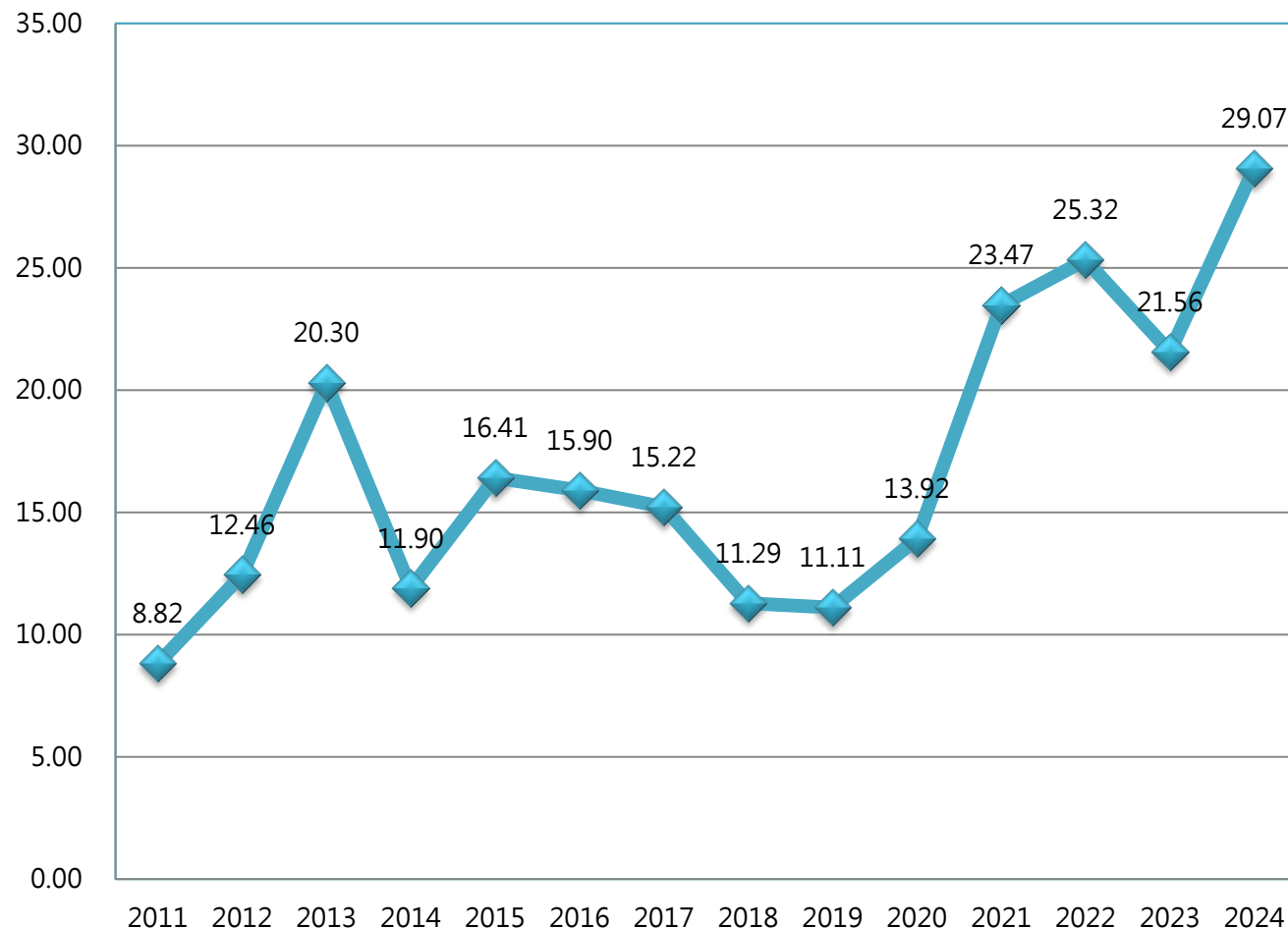
- Smart Monitor System for manufacturing Safety
- Engineering Data Analysis



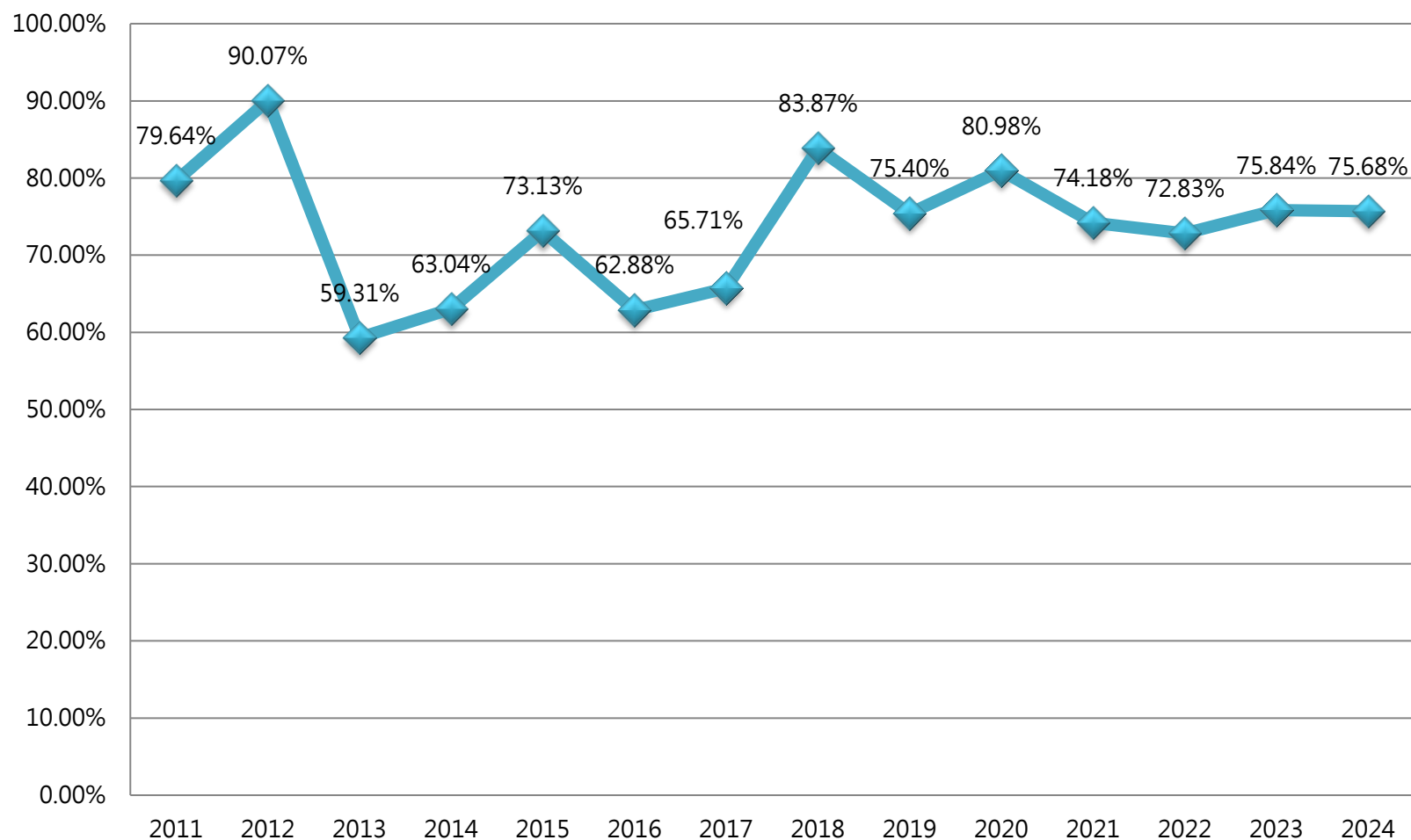


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歷年EPS趨勢



歷年股利配發率趨勢



THANKS

感 謝 聆 聽



弘塑集團